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### **ON Semiconductor**®

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SuperFET<sup>®</sup> III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing

charge balance technology for outstanding low on-resistance

and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switch-

ing performance, and withstand extreme dv/dt rate. Conse-

quently, SuperFET III MOSFET is very suitable for various

power system for miniaturization and higher efficiency.

### FCPF067N65S3 N-Channel SuperFET<sup>®</sup> III MOSFET 650 V, 44 A, 67 mΩ

### Features

- 700 V @ T<sub>J</sub> = 150 °C
- Typ. R<sub>DS(on)</sub> = 59 mΩ
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 78 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 715 pF)
- 100% Avalanche Tested
- RoHS Compliant

### Applications

- Telecom / Sever Power Supplies
- Industrial Power Supplies
- UPS / Solar



# 

Description

### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter			FCPF067N65S3	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		650	V		
V <sub>GSS</sub>		- DC		±30	V	
	Gate to Source Voltage	- AC	±30			
ID	Drain Current	- Continuous (T <sub>C</sub> = 25 <sup>o</sup> C)		44*	^	
		- Continuous (T <sub>C</sub> = 100 <sup>o</sup> C)		28*	A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	110*	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)			214	mJ	
I <sub>AS</sub>	Avalanche Current	4.8	А			
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)			0.46	mJ	
dv/dt	MOSFET dv/dt			100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)			20		
P <sub>D</sub>	Rower Dissinction	(T <sub>C</sub> = 25°C)	$(T_{\rm C} = 25^{\rm o}{\rm C})$		W	
	Power Dissipation	- Derate Above 25°C		0.37	W/ºC	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C	

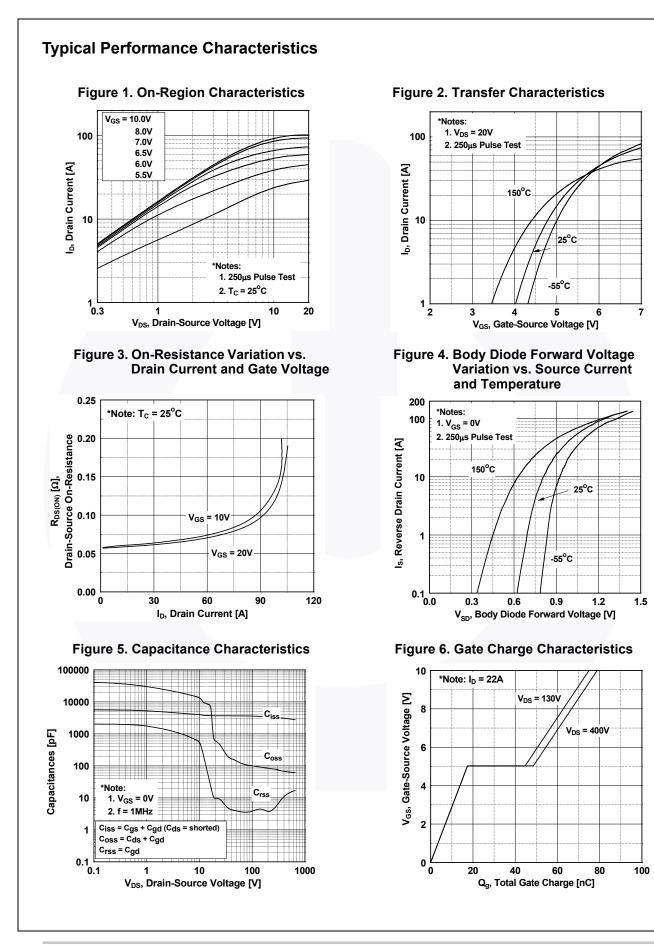
\*Drain current limited by maximum junction temperature.

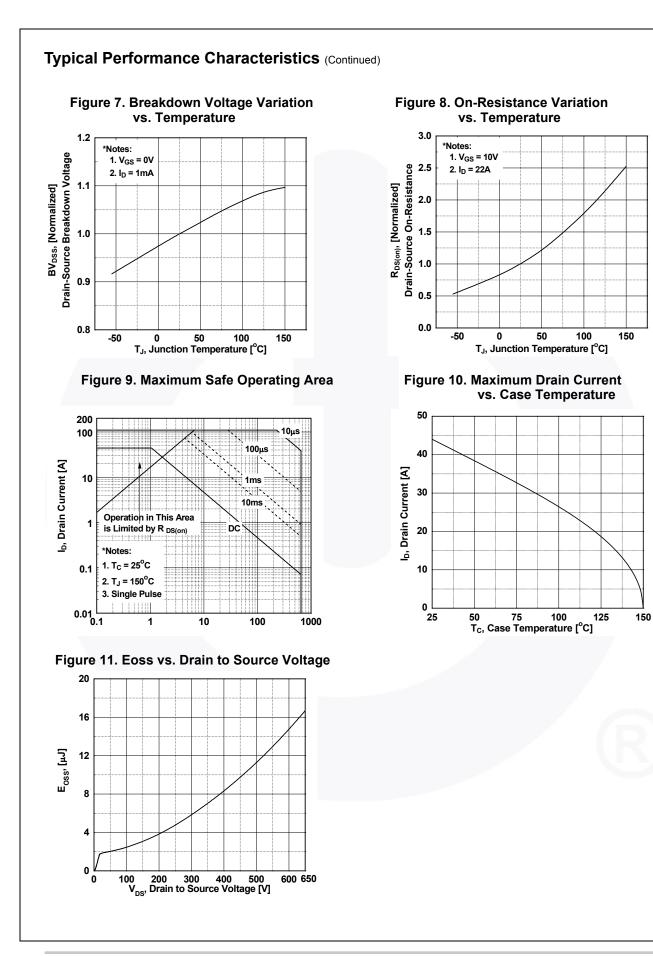
### **Thermal Characteristics**

Symbol	Parameter	FCPF067N65S3	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	2.7	°C/W
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	°C/W

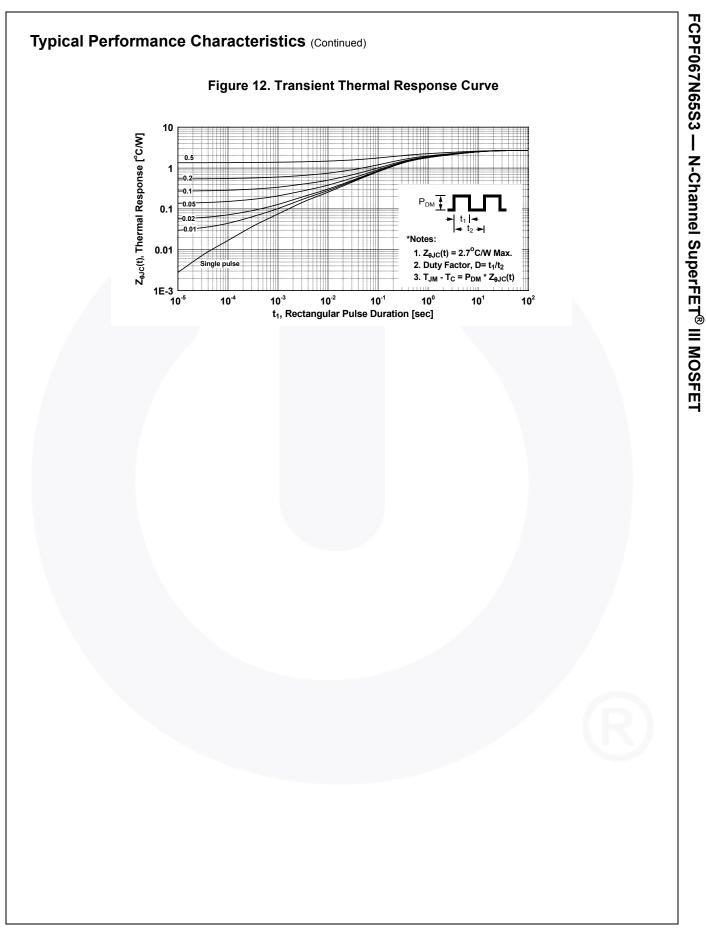
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165S3 — N
<b>I</b> -Channel
annel SuperFET <sup>®</sup>
r® III MOSFET

65S3 FCPF067N65S3 Characteristics T <sub>C</sub> = Parameter eristics Drain to Source Breakdown Vo	25°C unless	s otherwise noted Test C		N/A	Min.	N/A Typ.	50 Max.	units Unit
Parameter eristics Drain to Source Breakdown Vo		Test C			Min.	Тур.	Max.	Unit
Parameter eristics Drain to Source Breakdown Vo		Test C			Min.	Тур.	Max.	Unit
<b>Pristics</b> Drain to Source Breakdown Vo	ultage							
Drain to Source Breakdown Vo	oltage							
	oltage							1
	JILAUG	$\frac{V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}}{V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 150^{\circ}\text{C}}$			650	-	-	V
3reakdown Voltage Temperati	Ū.				700	-	-	V
Breakdown Voltage Temperature Coefficient		I <sub>D</sub> = 1 mA, Refe	renced to 2	25°C	-	0.72	-	V/ºC
Joemolent		V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V			-	-	1	
Zero Gate Voltage Drain Curre	ent	$V_{DS} = 630 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 520 \text{ V}, T_{C} = 125^{\circ}\text{C}$		_	2.2	-	μA	
Gate to Body Leakage Current							+100	nA
Land to Lody Loundge outfoll	-	- GS 200 V, V						
ristics								
Gate Threshold Voltage		$V_{GS} = V_{DS}, I_{D} =$	4.4 mA		2.5	-	4.5	V
Static Drain to Source On Resistance					-	59	67	mΩ
Forward Transconductance		V <sub>DS</sub> = 20 V, I <sub>D</sub> =	= 22 A		-	29	-	S
						1		1
aracteristics								
nput Capacitance		V <sub>DS</sub> = 400V, V <sub>C</sub>	<sub>3S</sub> = 0 V,		-	3090	-	pF
Dutput Capacitance						68	-	pF
Effective Output Capacitance		$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V			-	715	-	pF
Energy Related Output Capacitance		$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$			-	104	-	pF
Total Gate Charge at 10V		$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 22 \text{ A},$ $V_{GS} = 10 \text{ V}$			-	78	-	nC
Gate to Source Gate Charge				-	18	-	nC	
Gate to Drain "Miller" Charge				(Note 4)	-	30	-	nC
Equivalent Series Resistance		f = 1 MHz			-	0.6	-	Ω
haracteristics								
					- 1	26	-	ns
Turn-On Rise Time		V <sub>DD</sub> = 400 V, I <sub>D</sub>	= 22 A,			52	-	ns
urn-Off Delay Time		V <sub>GS</sub> = 10 V, R <sub>g</sub>	= 4.7 Ω		-	89	-	ns
urn-Off Fall Time		-		(Note 4)	-	16	_	ns
		<u> </u>		( ,	6			
n Diode Characteristic	S							
laximum Continuous Drain to	Source Diod	de Forward Curre	nt		-	-	44	Α
laximum Pulsed Drain to Sou	rce Diode Fo	orward Current			-	-	110	Α
rain to Source Diode Forward	J Voltage	$V_{GS}$ = 0 V, $I_{SD}$ =	= 22 A		-		1.2	V
Reverse Recovery Time		V <sub>GS</sub> = 0 V, I <sub>SD</sub> =	= 22 A,		-	435	-	ns
		dl <sub>F</sub> /dt = 100 A/μs					μC	
	ristics Gate Threshold Voltage Static Drain to Source On Res Forward Transconductance aracteristics Input Capacitance Dutput Capacitance Effective Output Capacitance Energy Related Output Capac Total Gate Charge at 10V Gate to Source Gate Charge Gate to Drain "Miller" Charge Equivalent Series Resistance haracteristics furn-On Delay Time Turn-On Rise Time Turn-Off Fall Time In Diode Characteristic Maximum Continuous Drain to Maximum Pulsed Drain to Sou	Gate Threshold Voltage Static Drain to Source On Resistance Forward Transconductance aracteristics nput Capacitance Dutput Capacitance Effective Output Capacitance Foral Gate Charge at 10V Gate to Source Gate Charge Gate to Drain "Miller" Charge Equivalent Series Resistance haracteristics furn-On Delay Time furn-Off Delay Time furn-Off Fall Time h Diode Characteristics	Sate to Body Leakage Current $V_{GS} = \pm 30 \text{ V}, V_{II}$ risticsVSate Threshold Voltage $V_{GS} = V_{DS}, I_D =$ Sate Threshold Voltage $V_{GS} = 10 \text{ V}, I_D =$ Static Drain to Source On Resistance $V_{GS} = 10 \text{ V}, I_D =$ Forward Transconductance $V_{DS} = 20 \text{ V}, I_D =$ aracteristics $V_{DS} = 400 \text{ V}, V_{CI}$ Imput Capacitance $V_{DS} = 400 \text{ V}, V_{CI}$ State to Source Output Capacitance $V_{DS} = 0 \text{ V to 40}$ Could Gate Charge at 10V $V_{DS} = 0 \text{ V to 40}$ Sate to Source Gate Charge $V_{GS} = 10 \text{ V}$ Sate to Drain "Miller" Charge $V_{GS} = 10 \text{ V}$ Sate to Drain "Miller" Charge $f = 1 \text{ MHz}$ Sate to Drain "Miller" Charge $f = 1 \text{ MHz}$ Sate to Drain "Miller" Charge $V_{DD} = 400 \text{ V}, I_D$ Sate to Drain "Miller" Charge $V_{GS} = 10 \text{ V}$ Sate to Drain "Miller" Charge $V_{DD} = 400 \text{ V}, I_D$ Sate to Drain Time $V_{DD} = 400 \text{ V}, I_D$ Sate to Drain Time $V_{DS} = 10 \text{ V}, R_g$ Sate to Drain Time $V_{DD} = 400 \text{ V}, I_D$ Sate to Drain Time $V_{CS} = 10 \text{ V}, R_g$ Sate to Drain Time $V_{CS} = 10 \text{ V}, R_g$ Sate to Drain Time $V_{DD} = 400 \text{ V}, I_D$ Sate to Drain Time $V_{CS} = 10 \text{ V}, R_g$ Sate to Drain to Source Diode Forward CurrentSate to Drain to Source Diode Forward CurrentSate to Drain to Source Diode Forward Current	Sate to Body Leakage Current $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$ risticsSate Threshold Voltage $V_{GS} = V_{DS}, I_D = 4.4 \text{ mA}$ Static Drain to Source On Resistance $V_{GS} = 10 \text{ V}, I_D = 22 \text{ A}$ Forward Transconductance $V_{DS} = 20 \text{ V}, I_D = 22 \text{ A}$ aracteristics $V_{DS} = 20 \text{ V}, I_D = 22 \text{ A}$ anacteristics $V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ Dutput Capacitance $V_{DS} = 0 \text{ V to 400 V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ Effective Output Capacitance $V_{DS} = 0 \text{ V to 400 V}, V_{GS} = 0 \text{ V}, GS = 0 \text{ V}, OS = 0 \text{ V to 400 V}, V_{GS} = 0 \text{ V}, S_{S} = 10 \text{ V}, S_{S$	Sate to Body Leakage Current $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$ risticsSate 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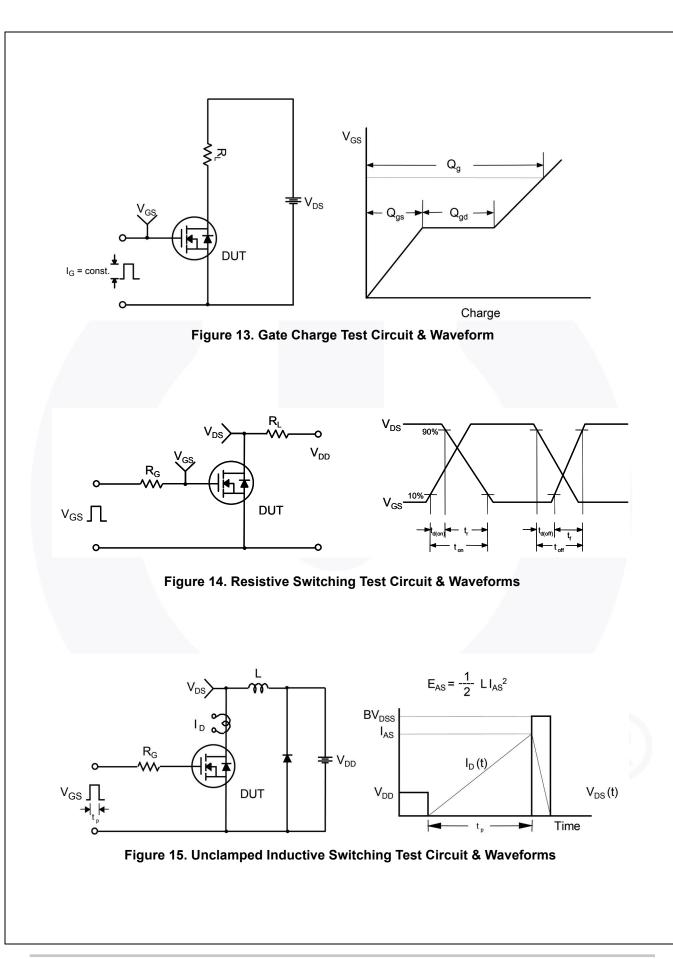




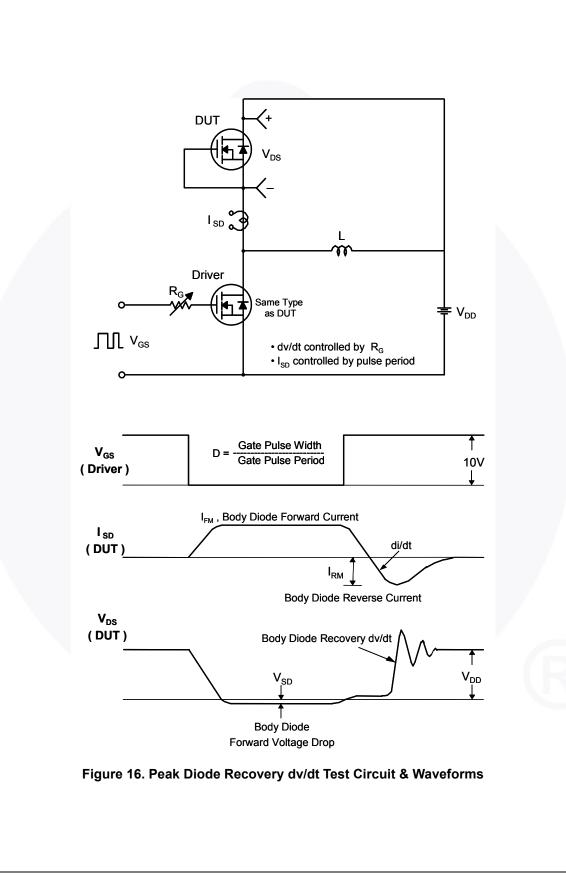
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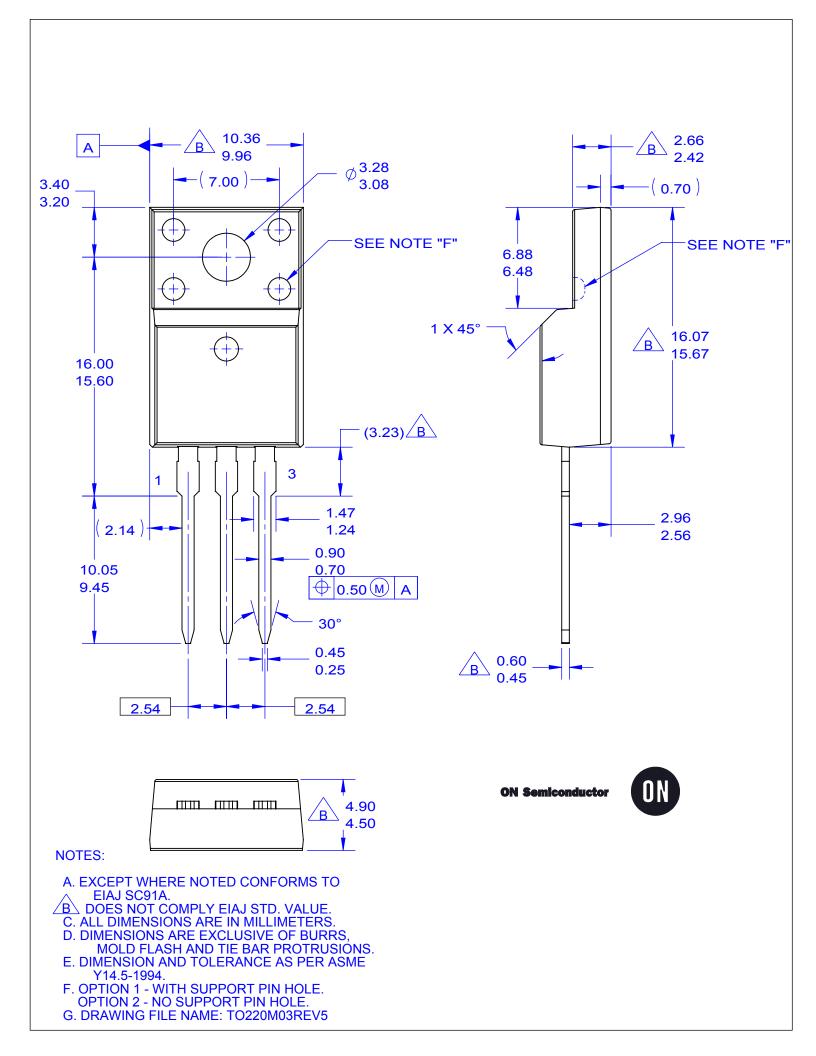


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